MMBFJ177LT1G

JFET Chopper

P-Channel – Depletion

Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Gate Voltage	V _{DG}	25	Vdc
Reverse Gate-Source Voltage	V _{GS(r)}	-25	Vdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

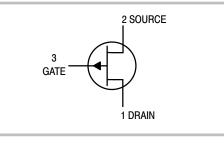
Total Device Dissipation FR-5 Board	PD	225	mW
(Note 1) T _A = 25°C Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

1. FR-5 = 1.0 \times 0.75 \times 0.062 in.



ON Semiconductor®

http://onsemi.com





MARKING DIAGRAM



6Y = Specific Device Code

- M = Date Code*
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBFJ177LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel

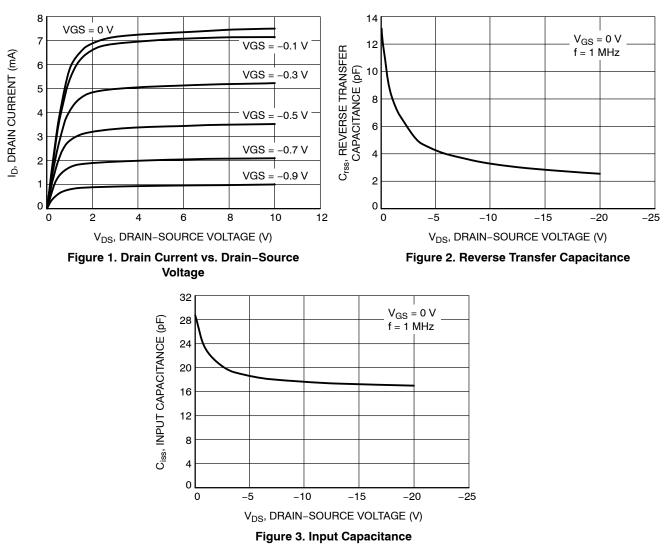
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBFJ177LT1G

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Char	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Gate-Source Breakdown Voltage (V_{DS} = 0, I_D = 1.0 µAdc)			30	-	Vdc
Gate Reverse Current (V _{DS} = 0 Vdc, V _{GS} = 20 Vdc)			-	1.0	nAdc
Gate Source Cutoff Voltage (V_{DS} = 15 V	V _{GS(off)}	0.8	2.5	Vdc	
ON CHARACTERISTICS					
Zero-Gate-Voltage Drain Current (V _{GS}	I _{DSS}	1.5	20	mAdc	
Drain Cutoff Current (V_{DS} = 15 Vdc, V_{GS}	I _{D(off)}	-	1.0	nAdc	
Drain Source On Resistance (I _D = 500 μ	r _{DS(on)}	-	300	Ω	
Input Capacitance	V _{DS} = 0, V _{GS} = 10 Vdc	C _{iss}	-	11	pF
Reverse Transfer Capacitance	f = 1.0 MHz	C _{rss}	-	5.5	

2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty Cycle \leq 2%.



TYPICAL CHARACTERISTICS

MMBFJ177LT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236AB) CASE 318-08 **ISSUE AP**

0.25

L

L1

VIEW C



D

Η_E

h

Ė

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2
- CONTROLLING DIMENSION: INCH. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH 3 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

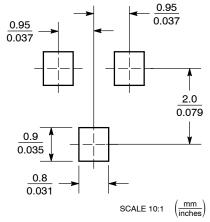
				1		
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
Г	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°



DRAIN

З. GATE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

Phone: 421 33 790 2910

Phone: 81-3-5773-3850

Japan Customer Focus Center

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative